JSCJ

MSDS Report

Report NO.: MG00001000008

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAC130SN04
Package Type :	PDFNWB5x6-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	3.19%
Lead Frame	Copper	7440-50-8	97.3317%	37.84%
	Fe	7439-89-6	2.4123%	
	P	7723-14-0	0.0790%	
	Zn	7440-66-6	0.1430%	
	Pb	7439-92-1	0.0290%	
	Ag	7440-22-4	0.0050%	
Die Attach	lead	7439-92-1	82.24%	19.63%
	Rosin, hydrogenated	65997-06-0	6.73%	
	tin	7440-31-5	2.91%	
	Terpineol	8000-41-7	3.31%	
	TRI(PROPYLENE GLYCOL) BUTYL ETHER	55934-93-5	3.67%	
	Reaction mass of :12-hydroxy-N	126098-16-6	0.61%	
	N-OLEOYLSARCOSINE	110-25-8	0.53%	
Wire1	Al	7429-90-5	99.99%	2.44%
	others	—	0.01%	
Wire2	Cu	7440-50-8	96.80%	3.31%
	Pd	7440-05-3	2.98%	
	Au	7440-57-5	0.22%	
Mold Compound	Silica	60676-86-0	85.00%	29.86%
	Epoxy Resin	85954-11-6	8.50%	
	Phenol Resin	29690-82-2	6.00%	
	Carbon Black	1333-86-4	0.50%	
Plating	Tin	7440-31-5	100.00%	3.73%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.